

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re application of: Wu et al.

Attorney Docket No.:
NOVLP097/NVLS-2906

Application No.: 10/807,680

Examiner: Not yet assigned

Filed: March 23, 2004

Group: 2812

Title: METHODS OF POROGEN REMOVAL
FOR POROUS LOW DIELECTRIC
CONSTANT FILMS USING PLASMA
TREATMENTS

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on July 10, 2007 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed:

Tara Hayden

INFORMATION DISCLOSURE STATEMENT
37 CFR §§1.56 AND 1.97(b)

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, copies of which are attached, may be material to examination of the above-identified patent application. Applicants submit these references in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make these references of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is: (i) filed within three (3) months of the filing date of the above-referenced application, (ii) believed to be filed before the mailing date of a first Office Action on the merits, or (iii) believed to be filed before the mailing of a first Office Action after the filing of a Request for Continued Examination under §1.114. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. NOVLP097).

Respectfully submitted,

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Form 1449 (Modified)

**Information Disclosure
Statement By Applicant**

(Use Several Sheets if Necessary)

Atty Docket No.

NOVLP097/NVLS-2906

Application No.:

10/807,680

Applicant

Wu et al.

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23.	U.S. Office Action mailed March 28, 2007, from U.S Application No. 10/820,525 [Atty Dkt No. NOVLP091/NVLS-2889].
24.	U.S. Office Action mailed January 24, 2007, from U.S Application No. 10/789,103 [Atty Dkt No. NOVLP094/NVLS-2919].
25.	U.S. Office Action mailed June 21, 2007, from U.S Application No. 10/789,103 [Atty Dkt No. NOVLP094/NVLS-2919].
26.	U.S. Notice of Allowance and Fee Due mailed December 19, 2006, from U.S. Application No. 10/800,409. [NOVLP098/NVLS-2907]
27.	U.S. Office Action mailed April 9, 2007, from U.S Application No. 10/800,409 [Atty Dkt No. NOVLP098/NVLS-2907].
28.	Niu et al., "Methods for Improving the Cracking Resistance of Low-K Dielectric Materials," Novellus Systems, Inc., Appl. No. 11/376,510, filed March 14, 2006, pages 1-28. [NOVLP099D1/NVLS-2896D1]
29.	U.S. Office Action dated May 22, 2007, from U.S. Application No. 11/376,510 [Atty Dkt: NOVLP099D1/NVLS-2896D1]
30.	U.S. Notice of Allowance and Fee Due mailed April 9, 2007, from U.S. Application No. 10/927,777. [NOVLP106/NVLS-2930]
31.	Allowed Claims from U.S. Application No. 10/927,777. [NOVLP106/NVLS-2930]
32.	U.S. Final Office Action mailed April 3, 2007, from U.S Application No. 10/941,502 [Atty Dkt No. NOVLP107/NVLS-2932].
33.	U.S. Notice of Allowance and Fee Due mailed December 20, 2005, from U.S. Application No. 10/860,340. [NOVLP099/NVLS-2896]
34.	Wu et al., "PECVD Methods for Producing Ultra Low-K Dielectric Films Using UV Treatment," Novellus Systems, Inc., Appl. No. 11/608,056, filed December 7, 2006, pages 1-34. [NOVLP196/NVLS-3238]
35.	Wu et al., "Methods for Improving Performance of ODC Films with Dielectric Constant < 4.0," Novellus Systems, Inc., Appl. No. 11/693,661, filed March 29, 2007, pages 1-46. [NOVLP200/NVLS-3269]

Examiner

Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Form 1449 (Modified) Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Atty Docket No.	NOVLP097/NVLS-2906
	Application No.:	10/807,680
	Applicant	Wu et al.
	Filing Date	March 23, 2004
	Group	2812
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U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	1.	2003/0224156	12.2003	Kirner et al.			
	2.	2003/0111263	06.2003	Fornof et al.			
	3.	2002/0132496	09.2002	Ball et al.			
	4.	6,662,631	12.2003	Baklanov et al.			
	5.	2006/0145305	07.2006	Boyanov et al.			
	6.	7,098,149	08.2006	Lukas et al.			
	7.	2006/0040507	02.2006	Mak et al.			
	8.	2005/0230834	10.2005	Schmitt et al.			
	9.	2006/0105566	05.2006	Waldfried et al.			
	10.	2004/0018717	01.2004	Fornof et al.			
	11.	2004/0213911	10.2004	Misawa et al.			
	12.	2004/0249006	12.2004	Gleason et al.			
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	14.	2006/0178006	08.2006	Xu et al.			
	15.	6,572,925 B2	06.2003	Zubkov et al.			
	16.	6,566,278 B1	05.2003	Harvey et al.			
	17.	6,413,583 B1	07.2002	Moghadam et al.			
	18.	6,407,013 B1	06.2002	Li et al.			
	19.	6,365,528 B1	04.2002	Sukharev et al.			

Foreign Patent or Published Foreign Patent Application

Examiner Initial		Document No.	Publication Date	Country or Patent Office	Class	Sub-Class	Translation	
	20.	WO 03/052794 A2	26.06.2003	PCT			Yes	No
	21.	WO 03/005429 A1	16.01.2003	PCT				

Other Documents

Examiner Initial	No.	Author, Title, Place (e.g. Journal) of Publication, Date
	22.	U.S. Office Action mailed November 30, 2006, from U.S Application No. 10/927,777 [Atty Dkt No. NOVLP106/NVLS-2930].

Examiner	Date Considered
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Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.